HIGH PERFORMANCE COMPUTING FOR MANUFACTURING
INTERNSHIP PROGRAM

HPC4MFG

DETAILS
- 10 consecutive weeks between May and September 2021.
- Stipend:
  - Undergraduate students $600/week
  - Graduate students $750/week.
- Travel reimbursement for up to $1000*
- Housing Allowance of $150/week*

*If living more than fifty miles, one-way, from assigned hosting laboratory

ELIGIBILITY
- Be a U.S. citizen AND at least 18 years old by May 1, 2021.
- Open to recent graduates, undergraduate and graduate students. Have or be pursuing a degree related to high performance computing.

APPLICATION DEADLINE
February 1, 2021 | 4 PM EST

APPLY NOW
HTTPS://WWW.ZINTELLECT.COM/OPPORTUNITY/DETAILS/DOE-EERE-HPC-2021

The HPC4Mfg Internship Program is sponsored by the Advanced Manufacturing Office (AMO) within the Office of Energy Efficiency & Renewable Energy.